CHANGE NOTIFICATION



Analog Devices, Inc. 1630 McCarthy Blvd., Milpitas, CA 95035-7417 (408) 432-1900

October 16, 2017

Dear Sir/Madam: PCN_101617

Subject: Notification of New Assembly Location for Additional SOT-223 Packaged Devices

Please be advised that the Analog Devices, Inc. (ADI) Milpitas, California has successfully qualified UTAC Malaysia (UMY), for assembling subject devices. UTAC Malaysia (UMY) is ISO9001, ISO14001, ISO18001, and TS16949 certified. A summary of UTAC Malaysia (UMY) capacity and LTC's qualification results are shown on the attached page. The facility was physically audited by ADI's quality engineer. ADI product assembled in UTAC Malaysia (UMY) can be identified by the plant code marked on the 2nd level packaging as "L" and country of origin as "MY" as shown in attached sample label. The first units assembled by UTAC Malaysia (UMY) will be shipped after December 16, 2017. The list of affected part numbers is shown on the attached page.

Additionally, Analog Devices, Inc. performs reliability testing on production lots in accordance with our Quick Reaction Reliability (QR2) Monitor Program. This monitor program is designed to provide fast feedback for possible reliability problems associated with package assembly. Please provide an expeditious approval to this PCN, so that ADI can build subject devices at UTAC Malaysia.

Should you have any questions or concerns, please contact your nearest Analog Devices sales representative or me at (408) 432-1900 ext. 2077 or by email at jason.hu@analog.com before December 16, 2017, at which time we will consider this change to be approved.

Sincerely,

Jason Hu

Quality Assurance Engineer

For questions on this PCN, please contact Jason Hu or you may send an email to your regional contacts below or contact your local ADI sales representatives.

Americas: PCN_Americas@analog.com Europe: PCN_Europe@analog.com Japan: PCN_Japan@analog.com

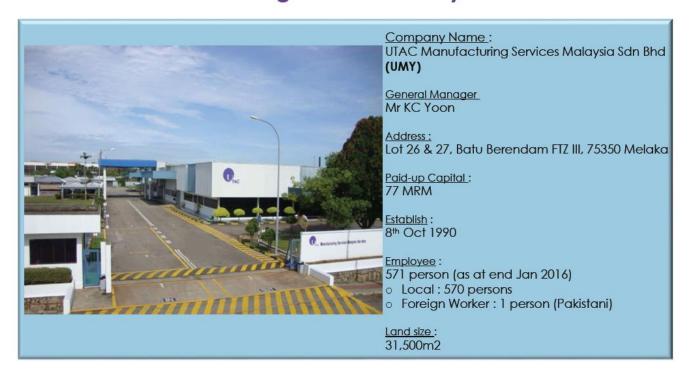
Rest of Asia: PCN_ROA@analog.com

Packaging Label



UTAC Malaysia (UMY) Capacity Summary

UTAC Manufacturing Services Malaysia Sdn Bhd



UMY Overview

Leverage UTAC's Capability and Location to Grow Legacy Packages

Key Highlights

- · Shipped >200 Mu Automotive Grade
- Shipped 4.4 billion units in 2015 with outstanding delivery performance > 95% and low ppm outgoing quality (<1ppm)
- Continue to meet/exceed stringent Japanese end customers requirements for > 25 years:
 - Toyota, Hitachi, Honda, Mazda
- Received Quality Excellence Award from Toyota for 2015.

Facility Snapshot				
Established	1990			
Location	Malacca, Malaysia			
Facility size (M²) Land area Floor area Open Floor area	c.31.5k c.9.2k 25%			
No. of staff (#)	c.571			
Operational Certifications	ISO9001:2008 (2012), TS16949:2009 (2012), ISO14001:2004 (2013), ISO18001:2007 (2013)			



FY15 Segment Splits

Full Assembly & Test Turnkey Automo



■Assembly & Test ■Test

Automotive vs. Non-Auto



■Automotive ■Non-Auto

Capacity

Assembly	Capacity (ku/day)		
SOT (SMD)	17,000		
TO (Power)	4140		

Equipment (Type)	Equipment (Number)		
Wire Bonders (Au Wire)	99		
Testers (Custom)	116		

UMY's History

Leverage UTAC's Capability and Location to Grow Legacy Packages

Overview

- Acquired as part of UTAC Group's acquisition of three manufacturing facilities from Panasonic in 2014
- Automotive Grade Production Certified;
- Panasonic's Japanese heritage provides familiarity with manufacturing best practices:
 - 5S, Kaizen (PDCA) 4M Change, QCC Activities and Toyota Way









RELIABILITY DATA UTAC Malaysia (UMY) as 2nd Source for SOT-223 Package 3/24/2017

3/24/2017							
• PRESSURE COOKER TEST AT 15 PSIG, +121°C							
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS	NUMBER OF FAILURES		
SOT-223	598 598	1641	1648	200.93 200.93	0		
• TEMP CYCLE FROM -65°C to +150°C							
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES		
SOT-223	600 600	1641	1648	600.00 600.00	0		
• THERMAL SHOC	K FROM -65°C to +	150°C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES		
SOT-223	600 600	1641	1648	600.00 600.00	0		
 HIGH TEMPERAT 	URE BAKE +175°C						
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS	NUMBER OF FAILURES		
SOT-223	100 100	1641	1648	100.00 100.00	0		
 SOLDER SHOCK 							
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE		NUMBER OF FAILURES		
SOT-223	200 200	1641	1648		0		
 POWER CYCLING 	G						
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES		
SOT-223	92 92	1641	1648	920.00 920.00	0 0		

Note: PCT, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL Preconditioning

Form: 00-03-6209B.

Rev 0

List of affected part numbers					
1	LT1117CST#PBF	31	LT1521CST-3#PBF	61	LT3080EST
2	LT1117IST#PBF	32	LT1521CST-3	62	LT3080IST
3	LT1117CST-2.85#PBF	33	LT1521CST-3.3#PBF	63	LT3092EST#PBF
4	LT1117IST-2.85#PBF	34	LT1521CST-3.3	64	LT3092IST#PBF
5	LT1117CST-3.3#PBF	35	LT1521CST-5#PBF	65	LT3092MPST#PBF
6	LT1117IST-3.3#PBF	36	LT1521CST-5	66	LT3092EST
7	LT1117CST-5#PBF	37	LT1521IST-3#PBF	67	LT3092IST
8	LT1117IST-5#PBF	38	LT1521IST-3	68	LT3092MPST
9	LT1117CST	39	LT1521IST-3.3#PBF		
10	LT1117IST	40	LT1521IST-3.3		
11	LT1117CST-2.85	41	LT1521IST-5#PBF		
12	LT1117IST-2.85	42	LT1521IST-5		
13	LT1117CST-3.3	43	LT1963AEST-1.5#PBF		
14	LT1117IST-3.3	44	LT1963AEST-1.8#PBF		
15	LT1117CST-5	45	LT1963AEST-2.5#PBF		
16	LT1117IST-5	46	LT1963AEST-3.3#PBF		
17	LT1129CST-3.3#PBF	47	LT1963AEST-1.5		
18	LT1129IST-3.3#PBF	48	LT1963AEST-1.8		
19	LT1129MPST-3.3#PBF	49	LT1963AEST-2.5		
20	LT1129CST-5#PBF	50	LT1963AEST-3.3		
21	LT1129IST-5#PBF	51	LT1963EST-1.5#PBF		
22	LT1129CST-3.3	52	LT1963EST-1.5		
23	LT1129IST-3.3	53	LT1963EST-1.8#PBF		
24	LT1129MPST-3.3	54	LT1963EST-1.8		
25	LT1129CST-5	55	LT1963EST-2.5#PBF		
26	LT1129IST-5	56	LT1963EST-2.5		
27	LT1175CST-5#PBF	57	LT1963EST-3.3#PBF		
28	LT1175IST-5#PBF	58	LT1963EST-3.3		
29	LT1175CST-5	59	LT3080EST#PBF		
30	LT1175IST-5	60	LT3080IST#PBF		